

# HMC479ST89 / 479ST89E

v02.0710





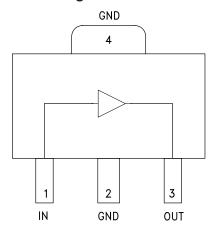
# SiGe HBT GAIN BLOCK MMIC AMPLIFIER, DC - 5 GHz

# Typical Applications

The HMC479ST89 / HMC479ST89E is an ideal RF/IF gain block & LO or PA driver:

- Cellular / PCS / 3G
- Fixed Wireless & WLAN
- CATV, Cable Modem & DBS
- Microwave Radio & Test Equipment

# **Functional Diagram**



#### **Features**

P1dB Output Power: +18 dBm

Gain: 15 dB

Output IP3: +33 dBm

Cascadable 50 Ohm I/Os

Single Supply: +5V to +12V

Industry Standard SOT89 Package

Included in the HMC-DK001 Designer's Kit

# **General Description**

The HMC479ST89 & HMC479ST89E are SiGe Heterojunction Bipolar Transistor (HBT) Gain Block MMIC SMT amplifiers covering DC to 5 GHz. Packaged in an industry standard SOT89, the amplifier can be used as a cascadable 50 Ohm RF/IF gain stage as well as a LO or PA driver with up to +20 dBm output power. The HMC479ST89 offers 15 dB of gain with a +33 dBm output IP3 at 850 MHz while requiring only 75 mA from a single positive supply. The Darlington feedback pair used results in reduced sensitivity to normal process variations and excellent gain stability over temperature while requiring a minimal number of external bias components.

# Electrical Specifications, Vs=8.0 V, Rbias=51 Ohm, $T_A=+25^{\circ} \text{ C}$

Parameter		Min.	Тур.	Max.	Units
	DC - 1.0 GHz	12.5	15		dB
	1.0 - 2.0 GHz	11.5	13.5		dB
Gain	2.0 - 3.0 GHz	10.5	12.5		dB
	3.0 - 4.0 GHz	9.5	11.5		dB
	4.0 - 5.0 GHz	8.5	10.5		dB
Gain Variation Over Temperature	DC - 5 GHz		0.008	0.012	dB/ °C
	DC - 1.0 GHz		12		dB
Input Peturn Loop	1.0 - 2.0 GHz		16		dB
Input Return Loss	2.0 - 4.0 GHz		18		dB
	4.0 - 5.0 GHz		22		dB
Output Return Loss	DC - 1.0 GHz		20		dB
Output Neturn Loss	1.0 - 5.0 GHz		22		dB
Reverse Isolation	DC - 5 GHz		18		dB
	0.5 - 1.0 GHz	15	18		dBm
	1.0 - 2.0 GHz	13	16		dBm
Output Power for 1 dB Compression (P1dB)	2.0 - 3.0 GHz	11	14		dBm
	3.0 - 4.0 GHz	10	13		dBm
	4.0 - 5.0 GHz	8	11		ubiii
	0.5 - 1.0 GHz		33		dBm
Output Third Order Intercept (IP3)	1.0 - 2.5 GHz		30		dBm
(Pout= 0 dBm per tone, 1 MHz spacing)	2.5 - 4.0 GHz		25		dBm
	4.0 - 5.0 GHz		23		dBm
Noise Figure	DC - 3.0 GHz		4.0		dB
Noise rigule	3.0 - 5.0 GHz		4.5		dB
Supply Current (Icq)			75		mA

Note: Data taken with broadband bias tee on device output.

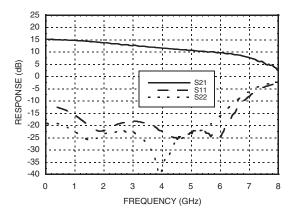


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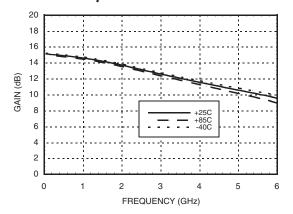


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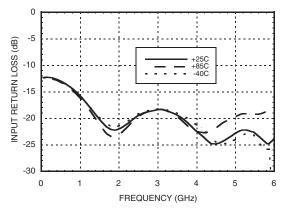
### **Broadband Gain & Return Loss**



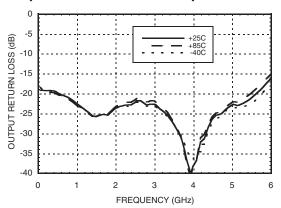
### Gain vs. Temperature



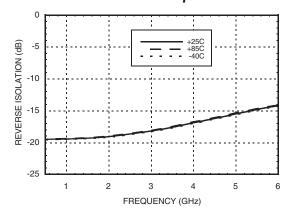
# Input Return Loss vs. Temperature



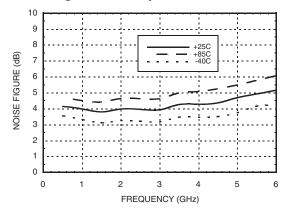
### **Output Return Loss vs. Temperature**



# Reverse Isolation vs. Temperature



# Noise Figure vs. Temperature



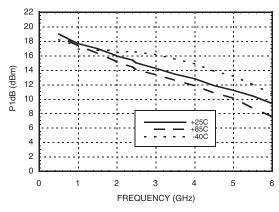


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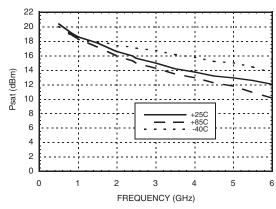


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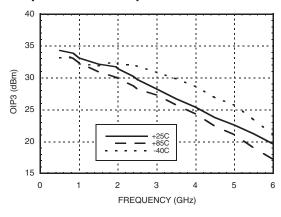
# P1dB vs. Temperature



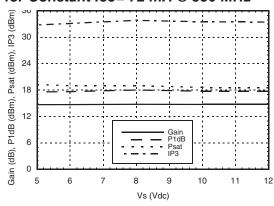
# Psat vs. Temperature



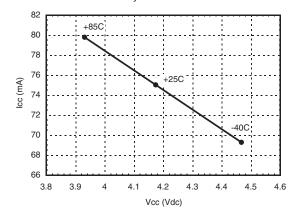
### Output IP3 vs. Temperature



# Gain, Power & OIP3 vs. Supply Voltage for Constant Icc= 72 mA @ 850 MHz



# Vcc vs. Icc Over Temperature for Fixed Vs= 8V, RBIAS= 51 Ohms





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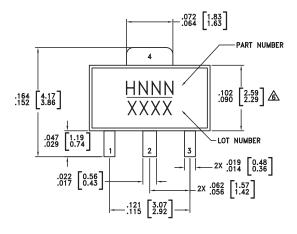
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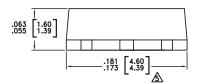
# **Absolute Maximum Ratings**

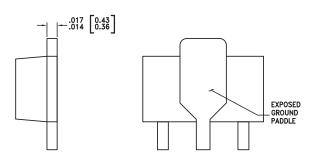
Collector Bias Voltage (Vcc)	+6.0 Vdc	
RF Input Power (RFIN)(Vcc = +4.2 Vdc)	+17 dBm	
Junction Temperature	150 °C	
Continuous Pdiss (T = 85 °C) (derate 14.76 mW/°C above 85 °C)	0.960 W	
Thermal Resistance (junction to lead)	67.6 °C/W	
Storage Temperature	-65 to +150 °C	
Operating Temperature	-40 to +85 °C	



# **Outline Drawing**







#### NOTES

- PACKAGE BODY MATERIAL:
   MOLDING COMPOUND MP-180S OR EQUIVALENT.
- 2. LEAD MATERIAL: Cu w/ Ag SPOT PLATING.
- 3. LEAD PLATING: 100% MATTE TIN.
- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 7. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

### Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC479ST89	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H479 XXXX
HMC479ST89E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	<u>H479</u> XXXX

- [1] Max peak reflow temperature of 235  $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260  $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX



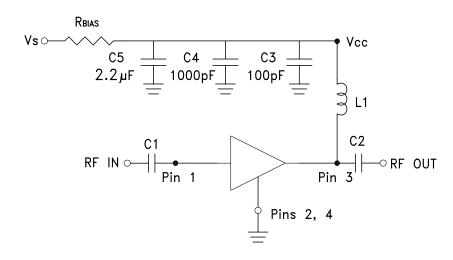


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### **Pin Descriptions**

Pin Number	Function	Description	Interface Schematic
1	RFIN	This pin is DC coupled. An off chip DC blocking capacitor is required.	RFOUT
3	RFOUT	RF output and DC Bias (Vcc) for the output stage.	
2, 4	GND	These pins and package bottom must be connected to RF/DC ground.	GND =

# **Application Circuit**



# Recommended Bias Resistor Values for Icc= 75 mA, Rbias= (Vs - Vcc) / Icc

Supply Voltage (Vs)	5V	6V	8V	10V	12V
RBIAS VALUE	13 Ω	27 Ω	51 Ω	82 Ω	110 Ω
RBIAS POWER RATING	1/8 W	1/4 W	1/2 W	1/2 W	1 W

#### Note:

- 1. External blocking capacitors are required on RFIN and RFOUT.
- 2. RBIAS provides DC bias stability over temperature.

# Recommended Component Values for Key Application Frequencies

Component	Frequency (MHz)						
Component	50	900	1900	2200	2400	3500	5000
L1	270 nH	56 nH	18 nH	18 nH	15 nH	8.2 nH	6.8 nH
C1, C2	0.01 μF	100 pF					

# **ANALOG**DEVICES

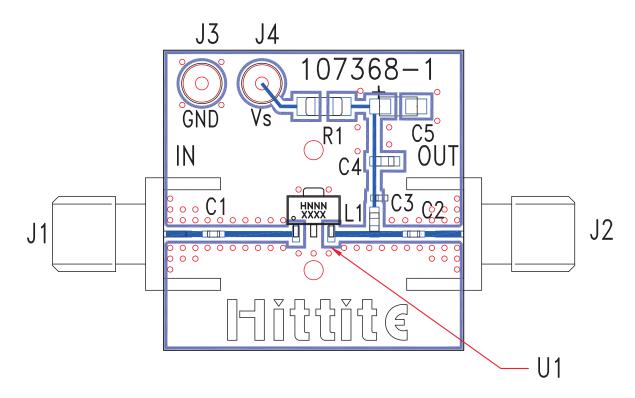
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### **Evaluation PCB**



### List of Materials for Evaluation PCB 108323 [1]

Item	Description	
J1 - J2	PCB Mount SMA Connector	
J3 - J4	DC Pin	
C1, C2	Capacitor, 0402 Pkg.	
C3	100 pF Capacitor, 0402 Pkg.	
C4	1000 pF Capacitor, 0603 Pkg.	
C5	2.2 µF Capacitor, Tantalum	
R1	Resistor, 1210 Pkg.	
L1	Inductor, 0603 Pkg.	
U1	HMC479ST89 / HMC479ST89E	
PCB [2]	107368 Evaluation PCB	

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and package bottom should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.